TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK3407

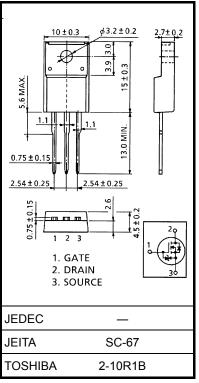
Switching Regulator Applications

Unit: mm

- Low drain-source ON resistance: RDS (ON) = 0.48Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 7.5 \text{ S (typ.)}$
- Low leakage current: $IDSS = 100 \mu A (max) (VDS = 450 V)$
- Enhancement-mode: $V_{th} = 2.4 \sim 3.4 \text{ V}$ ($V_{DS} = 10 \text{ V}$, $I_D = 1 \text{ mA}$)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	450	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	450	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1	l _D	10	Α	
	Pulse (Note 1	I _{DP}	40		
Drain power dissipat	ion (Tc = 25°C)	PD	40	W	
Single pulse avalanche energy (Note 2)		E _{AS}	222	mJ	
Avalanche current		I _{AR}	10	Α	
Repetitive avalanche energy (Note 3)		E _{AR}	4	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.9 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	3.125	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

- Note 1: Please use devices on condition that the channel temperature is below 150°C.
- Note 2: $V_{DD} = 90~V,~T_{ch} = 25^{\circ}C$ (initial), L = 3.7 mH, R_G = 25 $\Omega,~I_{AR} = 10~A$
- Note 3: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.



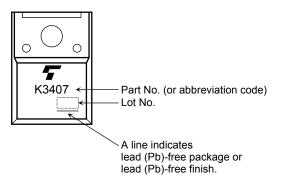
Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Gate-source brea	akdown voltage	V (BR) GSS	$I_G = \pm 10 \ \mu A, \ V_{DS} = 0 \ V$	±30	_	_	V
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 450 V, V _{GS} = 0 V	_	_	100	μА
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10$ mA, $V_{GS} = 0$ V	450	_	_	V
Gate threshold vo	oltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.4	_	3.4	V
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 5 A	_	0.48	0.65	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 5 A	3.5	7.5	_	S
Input capacitance	e	C _{iss}		_	1400	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	240	_	pF
Output capacitance		C _{oss}			590	_	
Switching time	Rise time	t _r	V_{GS} 0 V V_{GS} 0 V 0	_	35	_	
	Turn-on time	t _{on}		_	50	_	20
	Fall time	t _f		_	80	_	ns
	Turn-off time	t _{off}		_	260	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 360 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	_	35	_	
Gate-source charge		Qgs		_	19	_	nC
Gate-drain "miller" charge		Q _{gd}			16		

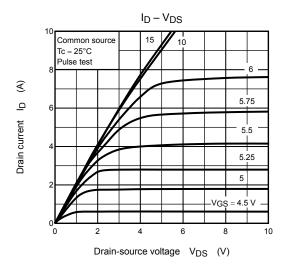
Source-Drain Ratings and Characteristics (Ta = 25°C)

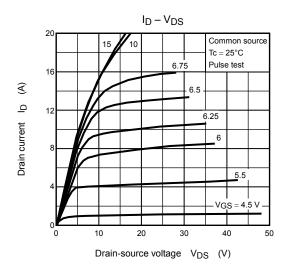
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	_	_	_	10	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	40	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 10 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 10 A, V _{GS} = 0 V,	_	280	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 100 A/μs	_	2.7	_	μС

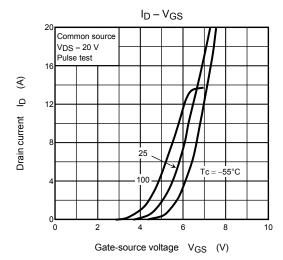
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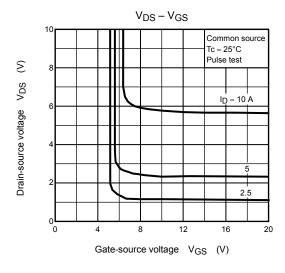


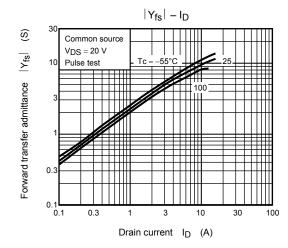
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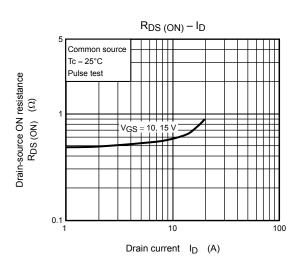


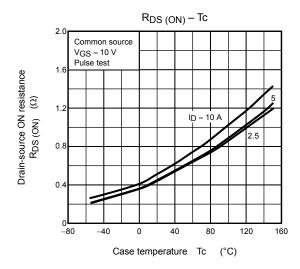


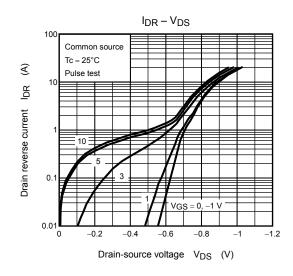


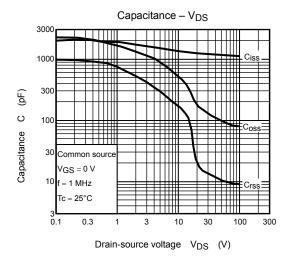


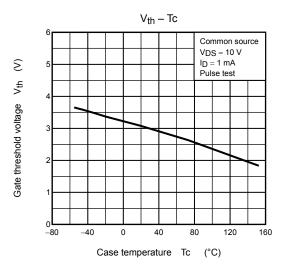


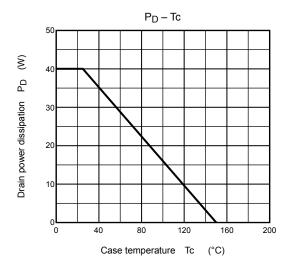


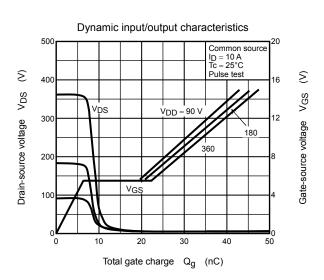


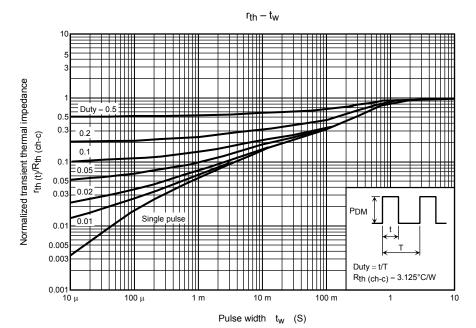


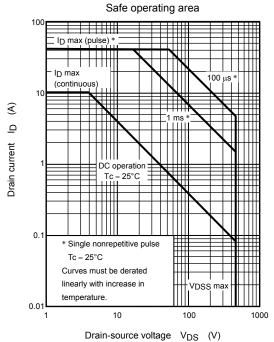


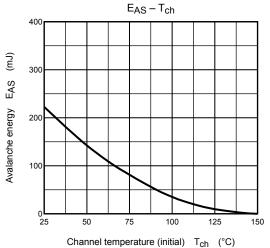


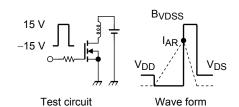












$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 3.7~mH \end{aligned} \qquad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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